



## BOARD LEVEL COOLING – 3742

3742 is a square pin fin board level heat sink designed to cool BGA and FPGA devices. Representative image only.

## ORDERING INFORMATION

| Part Number   | Device Type |
|---------------|-------------|
| 374224B60023G | BGA, FPGA   |

## HEAT SINK DETAILS

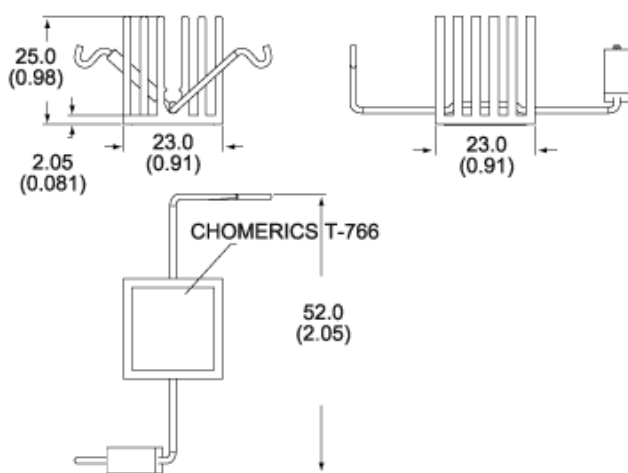
| Property                   | Details                                      |
|----------------------------|----------------------------------------------|
| Material                   | Aluminum                                     |
| Finish                     | Black Anodize                                |
| Device Attachment Options  | Solder Anchor Clip                           |
| Thermal Interface Material | T766 Chomerics Phase Change for All Surfaces |

| Property                     | Details              |
|------------------------------|----------------------|
| Heat Sink Width (mm)         | 23.0                 |
| Heat Sink Length (mm)        | 23.0                 |
| Heat Sink Height (mm)        | 25.0                 |
| Heat Sink Mounting Direction | Horizontal, Vertical |

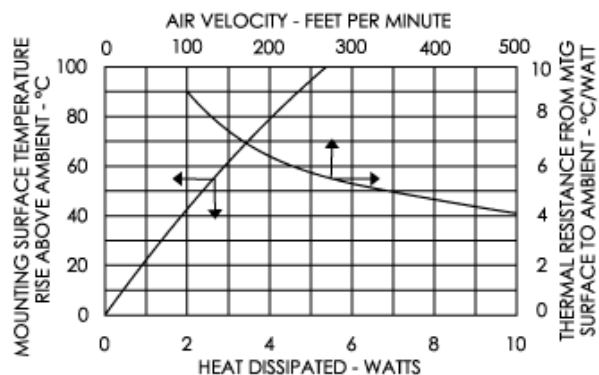
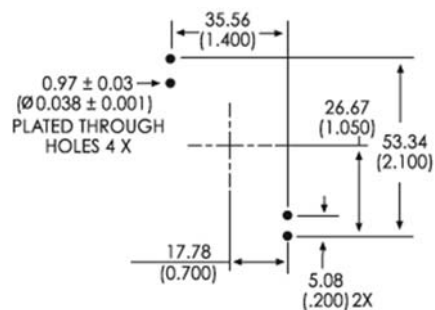


## MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)



Mounting Details:



# Mouser Electronics

Authorized Distributor

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Aavid:

[374224B60023G](#)